ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES INDUSTRIES	C, Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declarati he declaration e	on of the sub ncompasses a	stances w all lower	vithin the manufactur level materials for wh	er listed in hich the m	tem. Note: if nanufacturer	f the item is an as has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				als and Mfg Information				
Supplier Information													
Company name*	Company unique ID			Unique ID Authority				Response Date*					
onsemi										2024-04-16			
ontact Name Title - Contact			.]			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Re			- Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type
	NL17SZ	IL17SZ126XV5T2G ANA SNGL N		NINVERT 3 BUFF		2024-04-16		Cì	CN1		2.678	mg	Each
Manufacturing Proccess Informati	on		•					i		ŀ			·
Terminal Plating / Grid Array Mate	Terminal Plating / Grid Array Material Terminal Base Al		Alloy	J-STD-020 MSI	L Rating	Peak Proc	ess Body Ter	nperature	e Max Time at Peak	Temperat	ure Numb	er of Reflow Cyd	eles
Matte Tin (Sn) - annealed CU Alloy				1		260		С	30	secon	ds 3		
Comments													
level 1 - maximum time at peak temperatur	e during sol	dering is 10-3	0 seconds										
For more information regarding material co	omposition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg	
Lead Frame	1.22	mg	В	Nickel (Ni)	7440-02-0		0.4941	mg	
			Supplier	Iron (Fe)	7439-89-6		0.6771	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0488	mg	
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg	
Plating	0.003	mg	Supplier	Tin (Sn)	7440-31-5		0.003	mg	
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg	